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(54) Emulated EEPROM memory device and corresponding method

(57) The invention relates to a method and device to emulate the features of a EEPROM memory device of the type included into a memory macrocell (1) which is embedded into an integrated circuit comprising also a microcontroller and including a Flash EEPROM memory structure formed by a predetermined number of sectors (F0, F1, F2, F3, F4, F5), characterized in that at least two sectors (E0, E1) of the Flash memory structure are used to emulate EEPROM byte alterability.

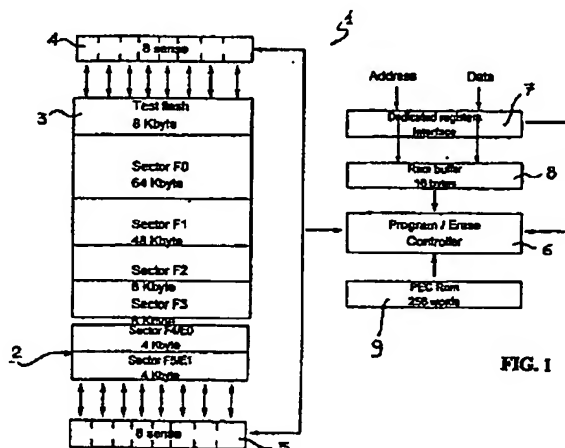


FIG. 1

Description

Technical Field

- 5 [0001] The present invention relates to a method and device to emulate the features of a EEPROM memory device.
 [0002] More specifically, the invention relates to an Emulated EEPROM memory device of the type included into a memory macrocell which is embedded into an integrated circuit comprising also a microcontroller and including a Flash EEPROM memory structure formed by a predetermined number of sectors.
 [0003] The invention relates, particularly but not exclusively, to microcontroller electronic devices having an on-board resident memory. More specifically, the device may be a microcontroller or a microprocessor having a resident (on-board) and integrated memory macrocell circuit.
 10 [0004] In the embodiment being described by way of example, the memory macrocell includes an embedded Flash memory portion to store programs and update codes for the microcontroller and an embedded EEPROM non-volatile memory portion to store data.

Background art

- [0005] As is well known, modern microcontroller are provided with on-board memory circuits to store both programs and data on the same IC.
 20 [0006] In this specific technical field there is a felt need to have at least an EEPROM portion of the memory macrocell to be used just as a non-volatile memory for parameter storage and for defining non-volatile pointers of the stored data.
 [0007] However, Flash and EEPROM technologies are not compatible and the higher integration degree and much lower cost of the Flash devices would suggest to realize memory macrocell including just Flash memory cells.
 [0008] The memory circuit structure should comprises three portions: a main Flash memory portion, a small OTP portion and an EEPROM memory portion.
 25 [0009] The Flash memory portion should include at least four sectors.
 [0010] Flash and EEPROM portions have respective sense amplifiers so that one memory portion can be read while the other memory portion is written. However, simultaneous Flash and EEPROM write operations are not allowed.
 [0011] Neither erasing of the EEPROM portion is possible while writing on the Flash portion.
 30 [0012] Flash memory devices may be electrically erased by erasing the whole memory portion; while the EEPROMs may be erased on a byte by byte basis.
 [0013] The memory macrocell has a register interface mapped in the memory area. All the operations are enabled through two control registers, one register FCR for the Flash (and OTP) portion operations and another one ECR for the EEPROM portion operations.
 35 [0014] The status of a write operation inside the Flash portion can be monitored by a dedicated status register.
 [0015] A known prior art solution allows the above operations by using an EEPROM software emulation addressing two Flash sectors which are dedicated to EEPROM emulation.
 [0016] At each data update a pointer is added to find the new data. When a Flash sector is full all the data are swapped to the other sector. An unused sector is erased in background.
 40 [0017] This solution presents good cycling performances in the same few bytes are continuously updated.
 [0018] However, there are also some drawbacks which are listed hereinafter:

the best emulation is obtained by a huge managing software, at least 20Kbyte, which must be stored in the same memory circuit;

- 45 it might be necessary to wait for erase suspend before accessing at the EEPROM for read and write operations; a long read access time has been experimented.

- [0019] A first object of the present invention is that of providing a new method for emulating an EEPROM memory portion by using a Flash memory portion.
 50 [0020] A further object of the present invention is to provide an innovative system which allows a Flash memory portion to emulate EEPROM byte alterability.
 [0021] Another object of the present invention is that of providing a memory device comprising a Flash memory portion which may be accessed as a EEPROM memory portion during read, write and erase operations.
 [0022] A further object of the present invention is that of providing microprocessor or a microcontroller having an on-board memory portion including Flash sectors emulating EEPROM byte alterability.
 55

Summary of the invention

[0023] The solution idea on which the invention is based is that of providing an EEPROM hardware emulation of a Flash memory portion.

5 [0024] According to this solution idea, the technical problem is solved by an integrated memory device of the type previously indicated and characterized in that at least two sectors of the Flash memory structure are used to emulate EEPROM byte alterability.

[0025] The feature and advantages of inventive method and device will appear from the following non-limiting description of a preferred embodiment given by way of example with reference to the annexed drawings.

10

Brief description of the drawings

[0026]

15 Figures 1 shows a schematic diagram of a memory macrocell including a Flash memory portion and an EEPROM hardware emulation according to the present invention;

Figure 2 shows a schematic diagram of the inside structure of the EEPROM emulated memory portion according to the invention;

Figure 3 shows a simplified and schematic view in greater detail of the EEPROM portion structure;

20 Figure 3A shows a simplified and schematic view of a register interface associated to the memory macrocell of Figure 1;

Figure 3B reports in a table form the addresses and size of each memory sector;

Figures 3C, 3D and 3E show a schematic view of a Flash Control Register of an EEPROM Control Register and of a Flash Status Register respectively;

25 Figure 4 is a high level flow-chart representing the steps of a method in accordance with the present invention;

Figure 4A shows a simplified and schematic view of a register interface associated to the EEPROM emulated portion of the present invention;

Figure 4B reports in a table form the addresses and size of each EEPROM memory sector;

30 Figures 4C, 4D and 4E show a schematic view of aFlash Control Register of an EEPROM Control Register and of a Flash Status Register respectively;

Figures 5 to 12 show simplified and schematic views of a series of updating phases concerning the EEPROM sectors of the memory macrocell according to the invention;

Figure 13 is a diagram of the write time versus the memory size for the memory of the present invention;

35 Figure 14 shows a simplified and schematic view of a state machine controlling an address counter inside the memory macrocell of the present invention.

Detailed description

40 [0027] With reference to the annexed drawing, with 1 is globally indicated a memory macrocell which is realized according to the present invention by a Flash EEPROM memory structure including an emulated EEPROM memory portion 2.

[0028] The memory macrocell 1 is embedded into an integrated circuit comprising also a microcontroller. The invention is specifically, but not exclusively, provided for an integrated microcontroller having an on-board non-volatile memory portion.

45 [0029] However, the principle of the invention may also be applied to an integrated memory circuit structure.

[0030] The memory macrocell 1 comprises a main 128 Kbyte Flash memory structure formed by a predetermined number of sectors, two of which are used to emulate EEPROM byte alterability. More specifically 8 Kbyte of the Flash memory portion are used to emulate 1 kbyte of an EEPROM memory portion.

50 [0031] Four sectors are provided for the Flash memory portion: a first 64 Kbyte sector F0; a second 48 Kbyte sector F1; a third 8 Kbyte sector F2 and a fourth 8 Kbyte sector F3.

[0032] A fifth 4 Kbyte sector F4 represents and corresponds to a first EEPROM emulated sector E0, while a sixth 4 Kbyte sector F5 represents and corresponds to a second emulated EEPROM sector E1.

[0033] An 8 Kbyte test portion 3 of the Flash memory macrocell 1 is provided to store test flags.

55 [0034] Sense amplifiers circuit portions 4 and 5 are provided at opposite sides of the memory macrocell 1, as shown in Figure 1.

[0035] Those sense amplifiers are connected to a program/erase controller 6 which cooperates with a dedicated registers interface 7 through a RAM buffer 8.

[0036] A 256 words ROM 9 is also connected to the controller 6.

[0037] The first and second EEPROM emulated sectors E0, E1 are each divided in four blocks BLOCK 0, ..., BLOCK3 of the same size. Figure 2 shows schematically the emulated EEPROM structure.

[0038] Each block is divided in up to sixtyfour pages and each page is formed by sixteen bytes.

[0039] According to the present invention, at each page update selected page data are moved to the next free block. When a sector is full, all the pages are swapped to the other sector.

[0040] Figure 3 shows a simplified and schematic view in which each block includes only four pages instead of the sixtyfour pages above mentioned. This simplified layout is used just to explain the EEPROM hardware emulation according to the invention.

[0041] Now, with specific reference also to the example of figure 5, the page updating procedure will be disclosed.

[0042] Each page inside each block must be identified to know in which block the updated page is. In this respect, a group of non-volatile pointers is used.

[0043] In each EEPROM sector E0, E1 some additional non-volatile memory locations are provided. Those locations are not accessible by the user.

[0044] Those locations are 256 Byte for each sector E0, E1 and are more than the amount strictly necessary to store the pointers. Only 66 locations are effectively used; 64 for the page pointers (one for each page) and other two for indicating the updating status of the other sector.

[0045] The above memory locations are programmed in the single bit mode (bit by bit); in other words, at each updating step different locations are programmed to "0" since in a Flash memory portion it's not possible to overwrite a memory location without a previous erasing of that location, but this would involve losing also the user's information.

[0046] The registers writing strategy must keep in consideration the fact that when a sector is erased even the registers included in that sector are erased too.

[0047] Therefore, the content of non-volatile registers is also stored in volatile memory locations to allow an efficient addressing of the EEPROM user's space.

[0048] The erasing phase is a time consuming operation for the periods of time which are normally acceptable for writing an EEPROM allocation. That's why the erasing phase is divided in a number of step corresponding to the number of blocks, which are four in this example.

[0049] In this manner the EEPROM sector complementary to the one under updating will be surely erased even in the worst case in which the same page is continuously updated. In other words, after four writing phases a swap on the other sector is required.

[0050] According to the invention, the specific erasing phase is divided in four steps providing respectively:

- a pre-programming phase to "0" of half a sector;
- a subsequent pre-programming to "0" of the other half sector;
- erasing plus erasing verify on a sample of cells;
- full erasing.

[0051] Moreover, since the EEPROM updating phase may require a certain number of steps, it has been provided for the setting of a one bit flag when the updating phase is started and for the setting of a different one bit flag when the updating phase is completed. This facilitates the recovery operation in case of a fault during updating.

[0052] Let's now consider the example of Figure 14 showing a state machine 15 (PEC) controlling an address counter 20 which receives as input control signals CTL_SIGN, INCREMENT coming from the state machine 15.

[0053] The address counter 20 is output connected to an internal address bus 21 which is inside the memory macro-cell 1.

[0054] The address counter 20 doesn't correspond to the usual address counter included into a Flash memory since it receives also control signals from the state machine 15 in order to control the loading of hard-coded addresses in volatile or non-volatile registers 25. The registers 25 may be read and updated by the microcontroller during a reset phase or by the state machine 15 after an EEPROM update.

[0055] The address bus 21 is connected to the input of a 16byte RAM buffer 22 which is used for the page updating of the EEPROM. This RAM buffer 22 includes also two additional byte 23, 24 to store the page address during the page updating phase and the swap step.

[0056] When the user's program requires to write one or more byte in the EEPROM memory portion, the RAM buffer 22 is charged. Each charged memory location of the RAM buffer 22 has a supplementary bit TOBEPROG which is set so that the state machine 15 is able to complete the charging phase with "old" data in non-flagged locations just checking the content of the TOBEPROG bit during a sub-routine "Page Buffer Filling" as will be later explained.

[0057] The state machine 15 is active for instance in controlling the EEPROM page updating phase through an algorithm which will be disclosed in detail hereinafter.

[0058] Flash and EEPROM memories operations are controlled through the register interface 7 mapped in memory, see for instance the segment 22h in Figure 3A.

[0059] Flash Write Operations allows to program (from 1 to 0) one or more bytes or erase (from 0 or 1 to 1) one or more sectors.

[0060] EEPROM Write Operations allows to program (from 0 or 1 to 0 or 1) one or more bytes or erase all the memory (from 0 or 1 to 1).

5 [0061] Set Protection Operations allows to set Access, Write or Test Mode Protections.

[0062] As previously disclosed, the memory 1 comprises three portions: four main Flash sectors F0, F1, F2 and F3 for code, a small OTP zone included into the Flash and an EEPROM portion 2. Figure 3B reports in a table form the addresses and size of each memory sector.

10 [0063] The last four bytes of the OTP area (211FFCh to 211FFFh) are reserved for the Non-Volatile Protection Registers and cannot be used as storage area.

[0064] The Flash memory portion, including the OTP, and the EEPROM have duplicated sense amplifiers 4, 5, so that one can be read while the other is written. However simultaneous Flash and EEPROM write operations are forbidden.

15 [0065] Both Flash and EEPROM memories can be fetched. Reading operands from Flash or EEPROM memories is achieved simply by using whatever microcontroller addressing mode with the Flash and in the EEPROM memory as source.

[0066] Writing in the Flash and in the EEPROM memories are controlled through the register interface 7 as explained hereinafter.

20 [0067] The memory macrocell 1 has a register interface 7 mapped in the memory space indicated with the segment 22h. All the operations are enabled through two control registers; A FCR (Flash Control Register) for the Flash (and OTP) operations and an ECR (EEPROM Control Register) for the EEPROM operations. Those registers are shown in Figures 3C and 3D respectively,

[0068] The status of a write operation inside the Flash memory can be monitored through a dedicated status registers: FSR (Flash Status Register) shown in Figure 3E.

25 1) FLASH MEMORY OPERATIONS

[0069] Four Write Operations are available for the Flash memory portion: Byte program, Page Program, Sector Erase and Chip Erase. Each operation is activated by a sequence of three instructions:

30

OR	FCR,	#OPMASK	Operation selection
LD	ADD,	#DATA	Address and Data load
OR	FCR,	#080h	Operation start

35

40 [0070] The first instruction is used to select the desired operation, by setting bits FBYTE, FPAGE, FSECT or FCHIP of FCR. The second instruction is used to choose the address to be modified and the data to be programmed. The third instruction is used to start the operation (set of bit FWMS of FCR).

[0071] FWMS bit and the Operation Selection bit of FCR are automatically reset at the end of the Write operation.

[0072] Once selected, but non yet started (FWMS bit still reset), one operation can be cancelled by resetting the Operation Selection bit. The eventually latched addresses and data will be reset.

45 [0073] In the following, when non differently specified, let's suppose than the Data Page Pointer DPR0 has been set so to point to the desired 16Kbyte block to modify, while DPR1 has been set so to point to the Register interface:

50

SPP	#21		MMU paged registers
LD	R241,	#089h	Register Interface
LD	R240,	#000h	1st 16K page of Flash 0
LD	R240,	#001h	2nd 16K page of Flash 0
LD	R240,	#002h	3rd 16K page of Flash 0
LD	R240,	#003h	4th 16K page of Flash 0
LD	R240,	#004h	1st 16K page of Flash 1

55

(continued)

LD	R240,	#005h	2nd 16K page of Flash 1
LD	R240,	#006h	3rd 16K page of Flash 1
LD	R240,	#007h	Flash 2 and Flash 3
LD	R240,	#084h	OTP

A) Byte Program

[0074] The Byte program operation allows to program 0s in place of 1s.

OR	0400h,	#010h	Set FBYTE in FCR
LD	03CA7h,	#D6h	Address and Data load
OR	0400h,	#080h	Set FWMS in FCR

[0075] The first instruction is used to select the Byte Program operation, by setting bit FBYTE of FCR. The second instruction is used to specify the address and the data for the byte programming. The third instruction is used to start the operation (set of bit FWMS of FCR).

[0076] If more than one pair of address and data are given, only the last pair is taken into account. It's not necessary to use a word-wide instruction (like LDW) to enter address and data: only one byte will be programmed, but is unpredictable to know if it will be the low or the high part of the word (it depends on the addressing mode chosen).

[0077] After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FBYTE and FBUSY bits of FCR are automatically reset at the end of the Byte program operation (10 μ s typical).

[0078] The Byte Program operation is allowed during a Sector Erase Suspend, and of course not in a sector under erase.

B) Page Program

[0079] The Page Program operation allows to program 0s in place of 1s. From 1 to 16 bytes can be stored in the internal Ram before to start the execution.

OR	0400h,	#040h	Set FPAGE in FCR
LD	028B0h,	#0F0h	1st Address and Data
LD	028B1h,	#0E1h	2nd Add and Data (Opt.)
LD	028B2h,	#0D2h	3rd Add and Data (Opt.)
...
LD	028Bxh,	#0xdh	xth Add and Data (Opt.)
...
LD	028beh,	#01Eh	15th Add and Data (Opt.)
LD	028bfh,	#00Fh	16th Add and Data (Opt.)
OR	0400h,	#080h	Set FWMS in FCR

[0080] The first instruction is used to select the Page Program operation, by setting bit FPAGE of FCR. The second instruction is used to specify the first address and the first data to be programmed. This second instruction can be optionally followed by up to 15 instructions of the same kind, setting other addresses and data to be programmed. All the addresses must belong to the same page (only the four LSBs of address can change). Data contained in page

addresses that are not entered are left unchanged. The third instruction is used to start the operation (set of bit FWMS of FCR).

[0081] If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide instructions (like LDW) to enter address and data.

5 [0082] After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FPAGE and FBUSY bits of FCR are automatically reset at the end of the Page Program operation (160 us typical).

[0083] The Page Program operation is not allowed during a Sector Erase Suspend.

C) Sector Erase

10

[0084] The Sector Erase operation allows to erase all the Flash locations to 0ffh. From 1 to 4 sectors to be simultaneously erased can be entered before to start the execution. This operation is not allowed on the OTP area. It is not necessary to pre-program the sectors to 00h, because this is done automatically.

15

PP	#21		MMU paged registers
LD	R240,	#000h	1st 16K page of Flash 1
LD	R242,	#004h	1st 16K page of Flash 2
LD	R243,	#007h	Flash 2 and Flash 3

20

[0085] First DPR0 is set to point somewhere inside the Flash sector 0, DPR2 inside Flash sector 1, DPR3 inside Flash sectors 2 and 3. DPR1 continues to point to the Register interface.

25

OR	04000h,	008h	Set FSECT in FCR
LD	00000h,	000h	Flash 0 selected
LD	08000h,	000h	Flash 1 selected (Opt. 9)
LD	0C000h,	000h	Flash 2 selected (Opt. 9)
LD	0E000h,	000h	Flash 3 selected (Opt. 9)
OR	04000h,	080h	Set FWMS in FCR

30

35

[0086] The first instruction is used to select the Sector Erase operation, by setting bit FSECT of FCR. The second instruction is used to specify an address belonging to the first sector to be erased. The specified data is don't care. This second instruction can be optionally followed by up to three instructions of the same kind, selecting other sectors to be simultaneously erased. The third instruction is used to start the operation (set of bit FWMS of FCR).

40

[0087] Once selected, one sector cannot be deselected. The only way to deselect the sector, it to cancel the operation, by resetting bit FSECT. It is allowed to use word-wide instructions (like LDW) to select the sectors.

45

[0088] After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FSECT and FBUSY bits of FCR are automatically reset at the end of the Sector Erase operation (1,5 s typical).

[0089] The Sector Erase operation can be suspended in order to read or to program data in a sector not under erase. The Sector Erase operation is not allowed during a Sector Erase Suspend.

50 C.1) Sector Erase Suspend/Resume

[0090] The Sector Erase Suspend is achieved through a single instruction.

55

OR	0400h,	#004h	Set FSUSP in FCR
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EP 0 991 081 A1

[0091] This instruction is used to suspend the Sector Erase operation, by setting bit FSUSP of FCR. The Erase Suspend operation resets the Flash memory to normal read mode (automatically resetting bits FWMS and FBUSY) in a maximum time of 15µs. Bit FSECT of FCR must be kept set during the Sector Erase Suspend phase: if it is software reset, the Sector Erase operation is cancelled and the content of the sectors under erase is not guaranteed.

5 [0092] When in Sector Erase Suspend the memory accepts only the following operations: Read, Sector Erase Resume and Byte program. Updating the EEPROM memory is not possible during a Flash Sector Erase Suspend.

[0093] The Sector Erase operation can be resumed through two instructions:

10

AND	04000h,	#0FBh	Reset FSUSP in FCR
OR	04000h,	#080h	Set FWMS in FCR

15 [0094] The first instruction is used to end the Sector Erase Suspend phase, by resetting bit FSUSP of FCR. The second instruction is used to restart the suspended operation (set of bit FWMS of FCR). After this second instruction the FBUSY bit of FCR automatically set again.

D) Chip Erase

20

[0095] The Chip Erase operation allows to erase all the Flash locations to 0ffh. This operation is simultaneously applied to all the 4 Flash sectors (OTP area excluded). It is not necessary to pre-program the sectors to 00h, because this is done automatically.

25

OR	04000h,	#020h	Set FCHIP in FCR
OR	04000h	#080h	Set FWMS in FCR

30

[0096] The first instruction is used to select the Chip Erase operation, by setting bit FCHIP of FCR. The second instruction is used to start the operation (set of bit FWMS of FCR).

[0097] It is not allowed to set the two bits (FCHIP and FWMS) with the same instruction.

35 [0098] After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FCHIP and FBUSY bits of FCR are automatically reset at the end of the Chip Erase operation (3 s typical).

[0099] The Chip Erase operation cannot be suspended. The Chip Erase operation is not allowed during a Sector Erase Suspend.

2) EEPROM MEMORY OPERATIONS

40

[0100] Two Write Operations are available for the EEPROM memory: Page Update and Chip Erase. Each operation is activated by a sequence of three instructions:

45

OR	ECR,	#OPMASK	Operation selection
LD	ADD,	#DATA	Address and Data load
OR	ECR,	#080h	Operation start

50

[0101] The first instruction is used to select the desired operation, by setting bits EPAGE or ECHIP of ECR. The second instruction is used to choose the address to be modified and the data to be programmed. The third instruction is used to start the operation (set of bit EWMS of ECR).

55 [0102] EWMS bit and the Operation Selection bit of ECR are automatically reset at the end of the Write operation.

[0103] Once selected, but not yet started (EWMS bit still reset), one operation can be cancelled by resetting the Operation Selection bit. The eventually latched addresses and data will be reset.

[0104] In the following, when not differently specified, let's suppose that the Data Page Pointer DPR0 has been set

EP 0 991 081 A1

so to point to the EEPROM to modify, while DPR1 has been set so to point to the Register interface:

SPP	#21		MMU paged registers
LD	R241,	#089h	Register Interface
LD	R240,	#088h	EEPROM

[0105] It's important to note that the EEPROM operations duration are related to the EEPROM size, as shown in the table of Figure 4B.

A) Page Update

[0106] The page Update operation allows to write a new content. Both 0s in place of 1s and 1s in place of 0s. From 1 to 16 bytes can be stored in the internal Ram buffer before to start the execution.

OR	04001h,	#040h	Set EPAGE in ECR
LD	001C0g,	#0F0h	1st Address and Data
LD	001C1h,	#0E1h	2nd Add and Data (opt.)
LD	001C2h,	#0D2h	3rd Add and Data (opt.)
...	...		
LD	001Cxh,	#0xxh	xth Add and Data (opt.)
...	...		
LD	001ceh,	#01Eh	15th Add and Data (opt.)
LD	001cfh,	#00Fh	16th Add and Data (opt.)
OR	04001h,	#080h	Set EWMS in ECR

[0107] The first instruction is used to select the Page Update Operation, by setting bit EPAGE of EVR. The second instruction is used to specify the first address and the first data to be modified. This second instruction can be optionally followed by up to 15 instructions of the same kind, setting other addresses and data to be modified. All the addresses must belong to the same page (only the four LSBs of address can change). Data contained in page addresses that are not entered are left unchanged. The third instruction is used to start the operation 8set of bit EWMS of ECR).

[0108] If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide instructions (like LDW) to enter address and data.

[0109] After the second instruction the EBUSY bit of ECR is automatically set. EWMS, EPAGE and EBUSY bits of ECR are automatically reset at the end of the Page Update operation (30 ms typical).

[0110] The Page Update operation is not allowed during a Flash Sector Erase Suspend.

B) Chip Erase

[0111] The Chip Erase operation allows to erase all the EEPROM locations to 0ffh.

OR	04001h,	#020h	Set ECHIP in ECR
OR	04001h,	#080h	Set EWMS in ECR

[0112] The first instruction is used to select the Chip Erase operation, by setting bit ECHIP of ECR. The second

instruction is used to start the operation (set of bit EWMS of ECR).

[0113] It is not allowed to set the two bits (ECHIP and EWMS) with the same instruction.

[0114] After the second instruction the EBUSY bit of ECR is automatically set. EWMS, ECHIP and EBUSLY bits of ECR are automatically reset at the end of the Chip Erase operation (70 ms typical).

5 [0115] The Chip Erase operation cannot be suspended. The Chip Erase operation is not allowed during a Flash Sector Erase Suspend.

3) Protections Operations

10 [0116] Only one Write Operation is available for the Non Volatile Protection Registers: Set Protection operation allows to program 0s in place of 1s. From 1 to 4 bytes can be stored in the internal Ram buffer before to start the execution. This operation is activated by a sequence of 3 instructions:

15

OR	FCR,	#002h	Operation selection
LD	ADD,	#DATA	Address and Data load
OR	FCR,	#080h	Operation start

20

[0117] The first instruction is used to select the Set protection operation, by setting bit PROT of FCR. The second instruction is used to specify the first address and the first data to be programmed. This second instruction can be optionally followed by up to three interactions of the same kind, setting other addresses and data to be programmed. All the addresses must belong to the Non Volatile Protection registers (only the two LSBs of address can change). Protection Registers contained in addresses that are not entered are left unchanged. Content of not selected bits inside selected addresses are left unchanged, too. The third instruction is used to start the operation (set of bit FWMS of FCR).

25 [0118] If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide instructions (like LDW) to enter address and data.

[0119] After the second instruction the FBUSY bit of FCR is automatically set. FWMS, PROT and FBUSY bits of FCR are automatically reset at the end of the Set protection operation (40 μ s typical).

[0120] Once selected, but not yet started (FWMS bit still reset), the operation can be cancelled by resetting PROT bit. The eventually latched addresses and data will be reset.

30 [0121] The Set Protection operation is not allowed during a Sector Erase Suspend.

[0122] In the following, when not differently specified, let's suppose that the Data Page pointer DPR0 has been set so to point to the OTP area to modify, while DPR1 has been set so to point to the Register interface:

40

SPP	#21		MMU paged registers
LD	R241,	#089h	Register Interface
LD	R240,	#084h	OTP

45

[0123] There are three kinds of protections: access protection, write protections and test modes disabling.

3.1) Non Volatile Registers

50

[0124] The protection bits are stored in the last four locations of the OTP area (from 211FFCh to 211FFFh), as shown in Figure 4A. All the available protections are forced active during reset, then in the initialisation phase they are read from the OTP area.

55 [0125] The four Non Volatile Registers used to store the protection bits for the different protection features are one Time Programmable.

[0126] The access to these registers is controlled by the protections related to the OTP area where they are mapped.

3.2) set Access Protections

[0127] The Access Protections are given by bits APRA, APRO, APBR, APEE, APEX of NVAPR.

5

10

OR	04000h,	#002h	Set PROT in FCR
LD	01FFCh,	#0F1h	Prog WPRS3-1 in NVWPR
OR	04000h,	#080h	Set FWMS in FCR

[0128] The first instruction is used to select the Set Protection operation, by setting bit PROT of FCR. The second instruction is used to specify the NVAPR address and the new protection content to be programmed. The third instruction is used to start the operation (set of bit FWMS of FCR).

15

3.3) Set Write Protections

[0129] The Write Protections are given by bits WPBR, WPEE, WPRS3-0 of NVWPR.

20

25

OR	04000h,	#002h	Set Prot in FCR
LD	01FFDh,	#0F1h	Prog WPRS3-1 in NVWPR
OR	04000h,	#080h	Set FWMS in FCR

[0130] The first instruction is used to select the Set Protection operation, by setting bit PROT of FCR. The second instruction is used to specify the NVWPR address and the new protection content to be programmed. The third instruction is used to start the operation (set of bit FWMS of FCR).

30

[0131] The Write Protections can be temporary disabled by executing the Set Protection operation and writing 1 into these bits.

35

40

OR	01000h,	#002h	Set Prot in FCR
LD	01FFDh,	#0F2h	Prog WPRS0 in NVWPR Temp Unprotected WPRS1
OR	01000h,	#080h	Set FWMS in FCR

[0132] The Non Volatile content of the temporary unprotected bit remains unchanged, but now the content of the temporary unprotected sector can be modified.

45

[0133] To restore the protection it needs to reset the micro or to execute another Set protection operation and write 0 into this bit.

3.4) Disable Test Modes

50

[0134] The Test Mode Protections are given by bits TMDIS and PWOK of NVWPR.

55

OR	04000h,	#002h	Set PROT in FCR
LDW	01FFEh,	#05A7Ch	Prog NVPWD1-0

(continued)

OR	04000h,	#080h	Set FWMS in FCR
----	---------	-------	-----------------

- 5 [0135] The first instruction is used to select the Set Protection operation, by setting bit PROT of FCR. The second instruction must be word-wide and it is used to specify the NVPWD1-0 address and the password to be programmed. The third instruction is used to start the operation (set of bit FWMS of FCR). The second instruction automatically forces TMDIS bit of NVWPR to be programmed.
- 10 [0136] Once disabled the Test Modes can be enabled again only by repeating the disable test mode sequence with the right Password. If the given data is matching with the programmed password in NVPWD1-0, bit PWOK of NVWPR is programmed and Test Modes Are enabled again.
- [0137] If the given data is not matching, one of bits PWT2-0 of NVAPR is programmed. After three unmatching trials, when all bits PWT2-0 are programme, Test Modes are disabled for ever.
- 15 [0138] Just as an example, hereinafter a program erase controller algorithm for the Flash/EEPROM macrocell 1 is reported. This algorithm uses a call subroutine instructions named CAL and return from subroutine instructions named RET with four nested levels allowed.

Available Instructions:

20 ALT input ; Wait for input at 1
 CMP input ; Compare input and set a Flag if 1 (x3 instructions:
 three CMPi are existing, CMP1, CMP2, CMP3)
 JMP label ; Jump to label
 JIF label ; Jump to label if Flag = 1
 25 JFN label ; Jump to label if Flag = 0
 CAL label ; Call subr. (Store PC, Inc. SP and Jump to label)
 CLF label ; Call subr. if Flag = 1
 RET ; Return from subr. (Dec. SP and Jump to stored PC)
 STO output ; Set output at 1 (x5 instructions: 5 STOi instr. are
 30 existing, STO1, STO2, ... STO5) (this instr. is used to activate any
 Output signal of the PEC);

35

40

45

50

55

Input Variables:

5 NOTHING = No variables => Realize a NOP with CMP NOTHING;
 ALLO = All0 phase active
 ALLERASED = All sectors erased
 DATOOK = Data verified equal to the target
 ENDPULSE = End of Prog or Erase pulse
 10 ERSUSP = Erase Suspended
 LASTADD = Last Row or Column
 LASTSECT = Last Sector
 MAXTENT = Reached maximum tentative number allowed
 NORMOP = Normal Read conditions restored
 SOFTP = Soft Program phase active
 15 SUSPREQ = Erase Suspend request pending
 TOBEMOD = Sector to be erased or byte to be programmed
 VPCOK = Verify voltage reached by Vpcx;

 BYTERCY FF = Flash Byte Prog operation active or RECYCLE test mode
 CHIPER EE = EEPROM Chip Erase operation active
 20 CSERASE FF = Flash Sector/Chip Erase operation active
 NEWERPH0 = Erase phase 1-3 active
 NEWERPH1 = Erase phase 2-3 active
 NEEDERASE = Unused sector erase needed
 NEEDSWAP = Sector Swap needed
 PAGEPG EE = EEPROM Page Update operation active
 25 PAGENSF FF = Flash Page Prog operation active or NOSOFTptest mode
 SELPAGE = Selected Page to update
 SWAPFAIL = Swap error => autosuspend needed;

Output Variables:

30 NOTHING = No variables => Used to reset other variables;
 ALLO = Start/Stop All0 phase (toggle)
 CUIRES = Reset Command Interface and PEC
 ERASE = Start/Stop Erase phase (toggle)
 35 HVNEG = Start Erase pulse
 INCCOLM = Increment Column Address
 INCROW = Increment Row Address
 INCSECT = Increment Sector Address
 INCTENT = Increment tentative number
 LOADADD = Load column address from RAM BUFFER
 40 LOADSECT = Load sector address from RAM BUFFER
 PROGRAM = Start Prog pulse
 READSUSP = Stop the clock during erase suspend
 RESFLAG = Eliminate current sector from the list to be erased
 SOFTP = Start/Stop Soft Program phase (toggle)
 45 STOREADD = Store column address in RAM BUFFER
 SWXATVCC = Switch Vpcx at Vcc (read voltage)
 VERIFY = Set Verify mode
 VPCYON = Switch On/Off Vpcy pump (toggle);

 ENDSWAP = Reset NEEDSWAP (toggle)
 50 FORCESWAP = Force NEEDSWAP=1 (toggle)
 INCPAGE = Increment Page address
 LODATA = Load data from RAM buffer

55

```

LDNVCSS      = Load NVCSS address (from hardware)
LDNVESP      = Load NVESP address (from hardware)
LDOLDSECT    = Load Old sector address (from hardware)
5  LDPAGE     = Load Page address from RAM BUFFER
LDPAGE2      = Load Page address from RAM BUFFER (for Sector Swap)
LDVCSS       = Load VCSS address (from hardware)
LDVESP       = Load VESP address (from hardware)
PAGE         = Start/Stop Page Program phase (toggle)
10  READ      = Set/Reset read conditions (toggle)
STOREDATA    = Store read data into the RAM buffer
STOREPAGE    = Store page address in RAM BUFFER
STOREPAGE2   = Store page address in RAM BUFFER (for Sector Swap)
STOREPROT    = Store Protection data into the RAM buffer
STORESECT    = Store sector address in RAM BUFFER
15  SWAP      = Set/Reset Sector Swap phase (toggle)
WRITEVS      = Write Volatile Status;

```

Possible Operations:

```

20  Flash Byte Program           (1 nesting level)
Flash Page Program              (2 nesting levels)
Flash Chip/Sector Erase        (3 nesting levels)
Flash Byte Program while Erase Suspend (4 nesting levels)
Set Protections                (2 nesting levels)
25  EEPROM Page Update           (4 nesting levels)
EEPROM Chip Erase              (4 nesting levels)

```

```

30  CODE SIZE = 251 lines;

```

In this example, only EEprom Page Update will be described

MAIN PROGRAM:

```

35  CMP      PAGEPG_EE      ; EEPROM Chip Update op. selected ?
JIF      epgupd      ; If yes jump to EEPROM Chip update routine
JMP      main      ; If no, then loop

```

SUBROUTINES:

```

1) SDELAY (the PEC clock is used to count a delay for
analog signals settling)

```

```

45  CMP      NOTHING      ; NOP: delay cycle
CMP      NOTHING      ; NOP: delay cycle
CMP      NOTHING      ; NOP: delay cycle
CMP      NOTHING      ; NOP: delay cycle
50  RET                                ; 4 NOP + 1 CAL + 1 RET = 6 NOP

```

55

2) PROGRAM 1 BYTE (every byte is continuously programmed up to a positive verify test)

5

```

sbytepg
STO    VERIFY    ; Verify Data to be programmed
CMP    DATOOK    ; Compare read data with 00h
JIF    sbpend    ; If DATOOK=1 => Return (the data is already OK)
STO    PROGRAM   ; If DATOOK=0 => Apply Prog pulse
10    ALT    ENDPULSE ; Wait for end of Prog pulse
STO    INCTENT   ; If no Increment tentative number
CMP    MAXTENT   ; Compare tentative number with maximum allowed
JFN    sbytepg   ; If MAXTENT=0 => Retry
sbpend RET      ; If MAXTENT=1 || DATOOK=1 => Return

```

15

3) PROGRAM 1 PAGE

```

spagepg
20    STO    LDDATA    ; Read Data and flag TOBEPROG from RAM buffer
CMP    TOBEMOD    ; Byte to be programmed ?
JFN    sppincc    ; If no increment column
sppbyte
CAL    sbytepg    ; Byte Program
sppincc
25    STO    INCCOLM   ; Increment Column address
CMP    LASTADD    ; Last column ?
JFN    spagepg    ; If no restart program
RET      ; If yes Return

```

4) PROGRAM 1 SECTOR

30

```

sssectpg
CAL    sbytepg    ; Byte Program
STO    INCROW     ; Increment row
CMP    LASTADD    ; Last Row ?
JFN    sssectpg   ; If no continue All0
35    CMP    NOTHING ; NOP: delay cycle
STO    INCCOLM   ; Increment Column address
CMP    LASTADD    ; Last column ?
JFN    sssectpg   ; If no program again
RET      ; If yes Return

```

40

5) ERASE VERIFY 1 SECTOR (the sector is erased, read and verified byte after byte and after every erasing pulse starting from the last non erased byte; the subroutine terminates when the last byte of the sector is erased)

45

```

servfy
50    STO    VERIFY    ; Verify Data to be erased
CMP    DATOOK    ; Compare read Data with 0FFh

```

55

```

JFN      sevend      ; If DATOOK=0 => Return
STO      INCROW      ; If DATOOK=1 => Increment Row
5  CMP      LASTADD   ; Last Row ?
JFN      servfy      ; If no continue Erase Verify phase
STO      INCCOLM     ; If yes increment Column address
CMP      LASTADD     ; Last Column ?
JFN      servfy      ; If no continue Erase Verify phase
STO      RESFLAG     ; If yes the current sector is erased
10 sevend  RET        ; Return

```

EEPROM ROUTINES

15 1) PAGE BUFFER FILLING. This routine is used to fill all not selected addresses of the selected page with the old data written in those locations. Old Data are read from the old locations (using actual EESECT and EEBCK<1:0>, the

20 Volatile registers) using normal read conditions (Vpcx=4.5V) forced through signal READ.

25 Once Stored the old data in Ram, the local flag TOBEPROG for that byte is automatically set.

```

ebuffil
STO      READ        ; Enter Read mode conditions
30 ebfloop
STO      LDDATA      ; Read flag TOBEPROG from RAM buffer
CMP      TOBEMOD     ; Byte to be programmed ?
JIF      ebfinc      ; If yes increment column
STO      VERIFY     ; If no Read Old Data (STO3)
STO      STOREDATA   ; Store Old Data in Ram Buffer (STO2)
35 ebfinc
STO      INCCOLM     ; Increment Column address (STO5)
CMP      LASTADD     ; Last column ?
JFN      ebfloop     ; If no continue RAM filling
STO      READ        ; If yes exit Read mode
40 RET              ; Return

```

45 2) NON VOLATILE STATUS PROGRAM. This routine is used to program the Non Volatile Status Pointers NVESP, NVCSS0, NVCSS1.

```

estprg
CAL      sbytepg     ; Non Volatile Status Program
50 CMP      NOTHING   ; NOP: delay cycle
RET      ; Return

```

55

3) PAGE PROGRAM. This routine is used to program a Page taking the data from the RAM buffer. At first not selected page address in the Ram buffer are filled with the last valid data. Then the VIRG bit in NVESP is programmed to notify that the page program operation is started. Then after the page programming, the USED bit in NVESP is programmed to notify that the operation is concluded. At the end also the Volatile Block Pointers are updated

```

15  epagepg
    STO    STOREPAGE ; Store current Page Address in RAM
    CAL    ebuffil   ; Fill-in not selected page address
    STO    LDNVESP    ; Load New NVESP address for current page
    CAL    estprg     ; NVESP Program (VIRG bit)
    STO    LDPAGE     ; Load New Page address from RAM
20  CAL    spagepg    ; Page Program
    STO    LDNVESP    ; Load New NVESP address for current page
    CAL    estprg     ; NVESP Program (USED bit)
    STO    LDVESP     ; Load VESP address for current page (STO2)
    STO    WRITEVS    ; Write Volatile Status BCK<1:0> (STO3)
25  RET              ; Return

```

4) SECTOR SWAP. This routine is used when in the current sector the 4 blocks for the selected page are already used. In this case the selected page is programmed in the new sector and all the other unselected pages must be swapped to the new sector.

SWAP=1 forces TOBEPROG=0 => in ebuffil routine all the Page data are copied into the RAM buffer

CHIPER_EE=1 forces TOBEPROG=1 => in ebuffil routine all the data in the Ram buffer are kept at FFh (reset value).

CHIPER_EE=1 forces SELPAGE=0 => no page selected

```

45  esecswp
    STO    SWAP, PAGE ; Enter Sector Swap (STO4)
    esspage
    STO    LDPAGE2    ; Read selected page address from RAM (STO1)
50  CMP    SELPAGE    ; Current page is the selected for update ?
    JIF    essincp    ; If yes increment page
    CAL    epagepg    ; If no Page Program

```

55

```

essincp
STO    INCPAGE      ; Increment Page
5  CMP    LASTADD    ; Last Page ?
JFN    esspage      ; If no swap current page
CMP    SWAPFAIL     ; Swap fail ?
JIF    sexit        ; If yes autosuspend
STO    SWAP,PAGE    ; Exit Sector Swap phase
10  RET              ; Return

```

5) PROGRAM ALL0. This routine is used for program All0
This routine automatically program bit ACT of unused sector
when the sector swap is done.

```

eall0
STO    ALL0         ; Enter All0 phase (ST04)
STO    LDOLDSECT    ; Load Old Sector address (ST01)
20  CAL    ssectpg   ; Sector Program
STO    ALL0         ; Exit All0 phase
RET              ; Return

```

6) ERASE. This routine is used for erase. Erase verify is
made before the first erase pulse, since during Erase phase
3, the initial cells status is unknown.

```

30  eerase
STO    ERASE        ; Enter Erase phase (ST04)
STO    LDOLDSECT    ; Load Old Sector address (ST01)
eervfy
CAL    servfy       ; Erase Verify on all sector
35  CMP    ALLERASED ; All sector erased ?
JIF    eerend       ; If yes exit erase phase
eerpul
STO    HVNEG        ; If no apply Erase pulse
ALT    ENDPULSE     ; Wait for end of Erase pulse
CMP    NOTHING      ; NOP: reset the counter when HVNEG=1
40  STO    INCTENT   ; Increment tentative number
CMP    MAXTENT      ; Compare tentative number with maximum
allowed
JFN    eervfy       ; If MAXTENT=0 => erase verify
eerend
STO    ERASE        ; If MAXTENT=1 => exit Erase phase
45  RET              ; Return

```

7) SECTOR ERASE. This routine is used to enter the needed
erase phase on the unused sector, as explained by the
following table:

EPH<3:0>	EEERPH<1:0>	NEWERPH<1:0>	NEEDSWAP	NEEDERASE	Er.Phase
0000	11	00	0	0	None
0000(1111)	11	00	1	1	0
1110	00	01	0	1	1
1100	01	10	0	1	2
1000	10	11	0	1	3

;

Erase phase 0 makes the All0 on the second half (status included) (second half is programmed first just because it includes at the end of its 'address space' the NV status, whose bits must be programmed as soon as possible)

Erase phase 1 makes the All0 on the first half.

Erase phase 2 makes the Erase with verification of status only

Erase phase 3 completes the Erase

esector

```

20  STO     LDNVCSS      ; Load NVCSS0 address
    CAL     estprg      ; NVCSS0 Program (bit EPHS<3:0>)
    CMP     NEWERPH1    ;
    JFN     eseph01     ; If NEWERPH<1:0>=0X => Enter Erase Phase 0-1
    CAL     eerase      ; If NEWERPH<1:0>=1X => Enter Erase Phase 2-3
    CMP     NEWERPH0    ;
25  JFN     eseend      ; If NEWERPH<1:0>=10 => Exit Erase Phase 2-3
    eseph01
    CAL     eall0       ; Program All0 (needed before any erase)
    eseend
    STO     LDNVCSS      ; Load NVCSS0 address
    CAL     estprg      ; NVCSS0 Program (bit EPHE<3:0>)
30  STO     LDVCSS      ; Load VCSS0 address (STO2)
    STO     WRITEVS     ; Write Volatile Status ERPH<1:0> (STO3)
    CMP     NEEDSWAP    ;
    JFN     eseret      ; If NEEDSWAP=0 => exit Sector Erase
    STO     ENDSWAP     ; If NEEDSWAP=1 => ENDSWAP resets NEEDSWAP
    JMP     eseend      ; Program NVCS1 (CUR bit) and VCSS1 (EESCT)
35  eseret
    RET                ; Return

```

8) PAGE UPDATE. This routine is used to handle all the data transfers between blocks and sectors when an update of a page of the EEPROM is needed

epgupd

```

45  ALT     VPCOK        ; Wait for Vpcx verify voltage (was Read mode)
    STO     STOREPAGE2  ; Store Page address in RAM (Sect Swap) (STO2)
    STO     PAGE        ; Enter Page Program phase (STO4)
    CAL     epagepg     ; Selected Page Program
    STO     PAGE        ; Exit Page Program phase
    CMP     NEEDSWAP    ; EEPROM Sector Swap needed ?
    CLF     esecswp     ; If yes Sector Swap
50  CMP     NEEDERASE    ; Unused Sector Erase needed ?
    CLF     esector     ; Unused Sector Erase

```

JMP sexit ; Exit Page Update

5

[0139] The memory device and the method according to the invention allow a totally hardware emulation of an EEPROM memory portion.

[0140] No access differences are detectable between the emulated memory portion according to the invention and a standard EEPROM memory.

[0141] An immediate EEPROM access is available during the reading and writing phases of the emulated memory portion 2.

[0142] A further advantage is given by the Flash code execution running during EEPROM modify phase.

15 Claims

1. Emulated EEPROM memory device of the type included into a memory macrocell (1) which is embedded into an integrated circuit comprising also a microcontroller and including a Flash EEPROM memory structure formed by a predetermined number of sectors (F0, F1, F2, F3, F4, F5), characterized in that at least two sectors (E0, E1) of the Flash memory structure are used to emulate EEPROM byte alterability.

2. Emulated EEPROM memory device according to claim 1, characterized in that said EEPROM byte alterability is emulated by hardware means.

3. Emulated EEPROM memory device according to claim 1, characterized in that 8 Kbyte of the Flash memory portion are used to emulate 1 kbyte of an EEPROM memory portion.

4. Emulated EEPROM memory device according to claim 1, characterized in that first and second EEPROM emulated sectors (E0, E1) are each divided in a pre-determined number of blocks (BLOCK 0, ..., BLOCK3) of the same size and each block is divided in pages.

5. Emulated EEPROM memory device according to claim 1, characterized in that a state machine (15) is provided for controlling an address counter (20) which is output connected to an internal address bus (21) running inside the memory macrocell (1), said address counter (20) receiving control signals from the state machine (15) in order to control the loading of hard-coded addresses in volatile or non-volatile registers (25) which are read and updated by the microcontroller during a reset phase or by the state machine (15) after an EEPROM update.

6. Emulated EEPROM memory device according to claim 5, characterized in that said address bus (21) is connected to the input of a RAM buffer (22) which is used for the page updating of the EEPROM including two additional byte (23, 24) for storing the page address during a page updating phase.

7. Emulated EEPROM memory device according to claim 1, characterized in that Flash and EEPROM memories operations are controlled through a register interface (7) mapped into the memory (1).

8. Method for emulating the features of a EEPROM memory device incorporated into a memory macrocell (1) which is embedded into an integrated circuit comprising also a microcontroller and including a Flash EEPROM memory structure formed by a predetermined number of sectors (F0, F1, F2, F3, F4, F5), characterized in that at least two sectors (E0, E1) of the Flash memory structure are used to emulate EEPROM byte alterability by dividing each of said two sector in a pre-determined number of blocks (BLOCK 0, ..., BLOCK3) of the same size and each block in a predetermined number of pages and updating the emulated EEPROM memory portion programming different memory locations in a single bit mode.

9. Method according to claim 8, characterized in that at each page update selected page data are moved to the next free block and, when an EEPROM sector is full, all the pages are swapped to the other EEPROM sector.

10. Integrated microcontroller having an on-board non-volatile Flash EEPROM memory portion structure formed by a predetermined number of sectors, characterized in that at least two sectors of the Flash memory structure are used to emulate EEPROM byte alterability.

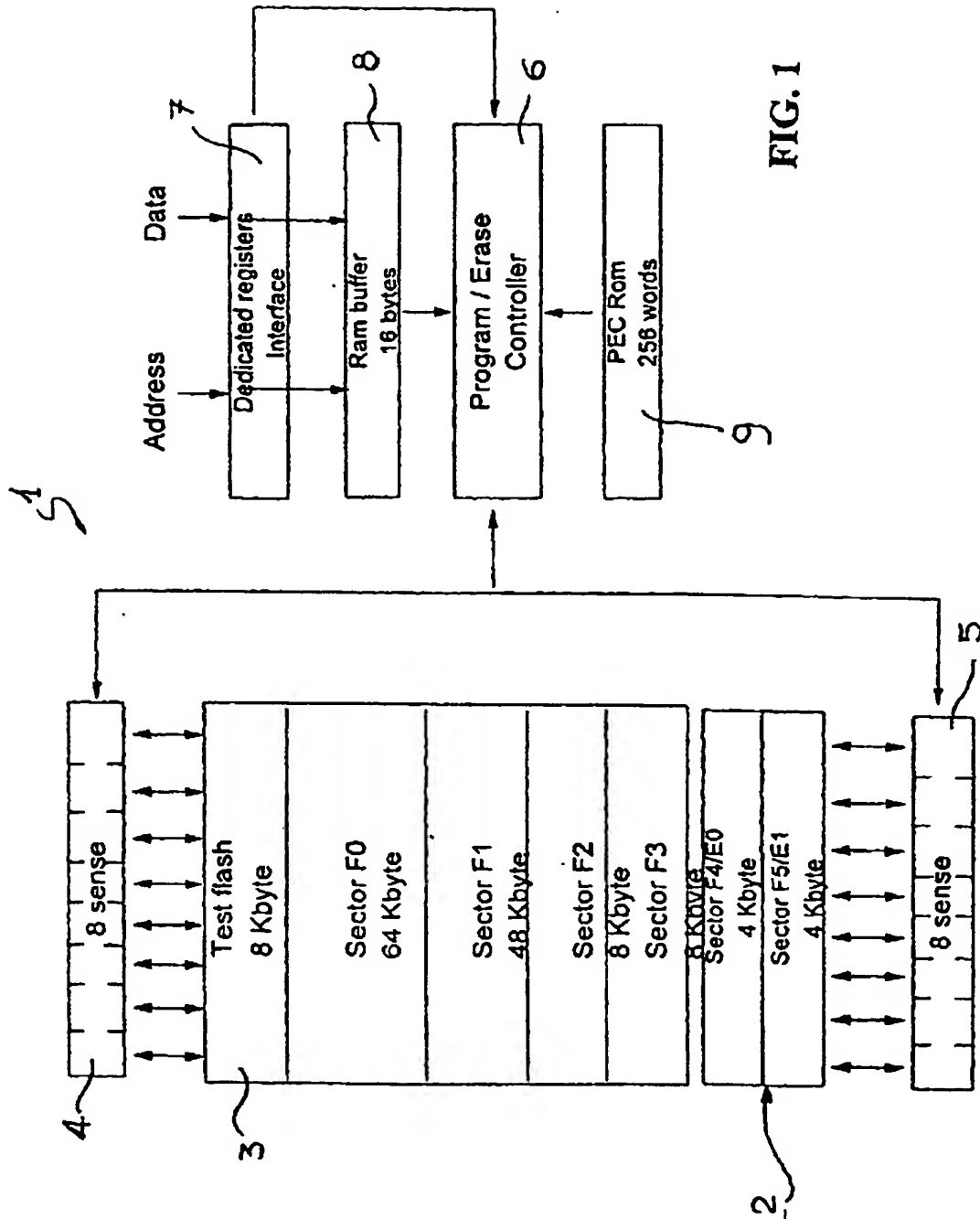


FIG. 1

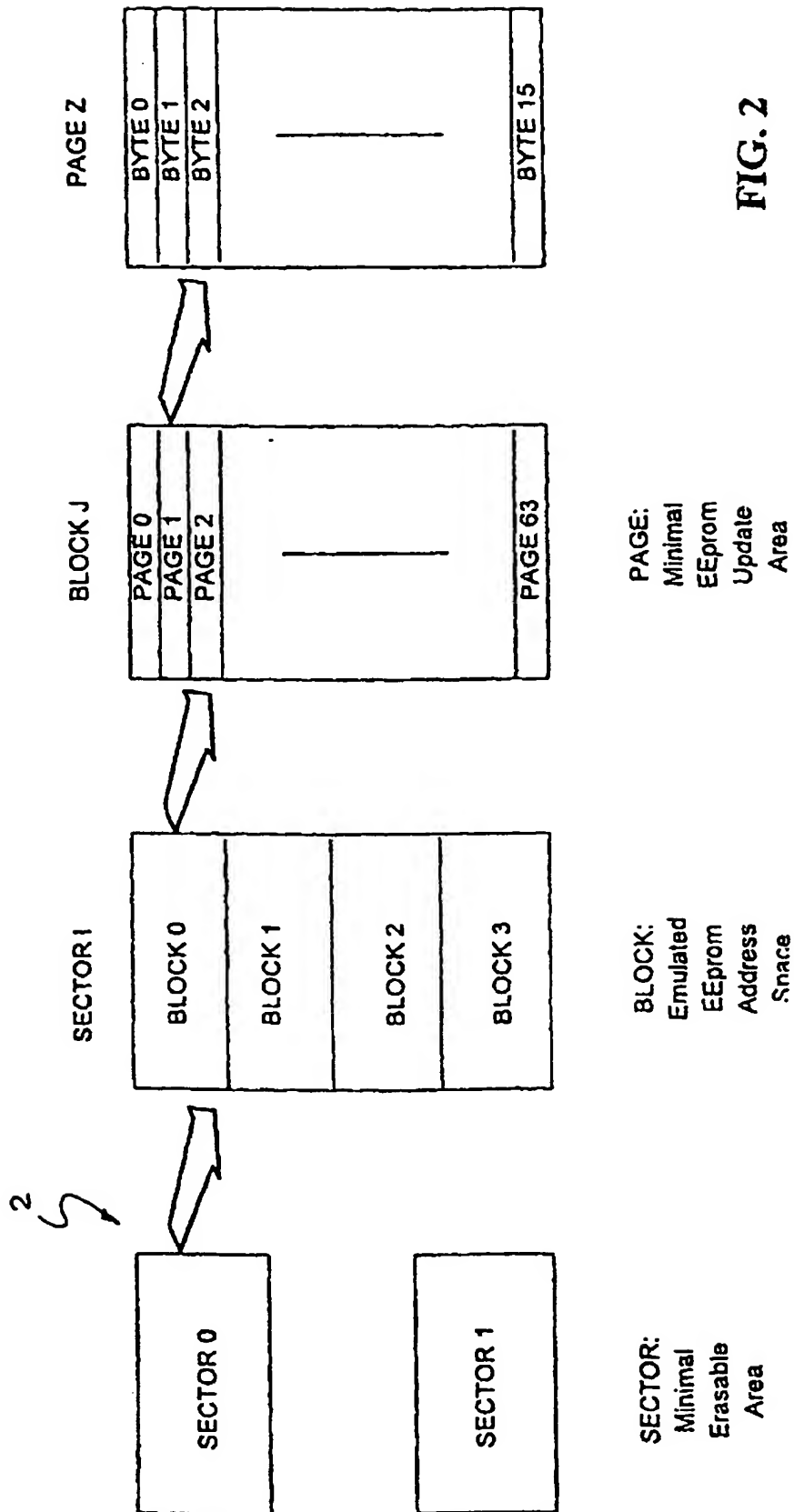


FIG. 2

Simplification: 4 pages (instead of 64) for each block

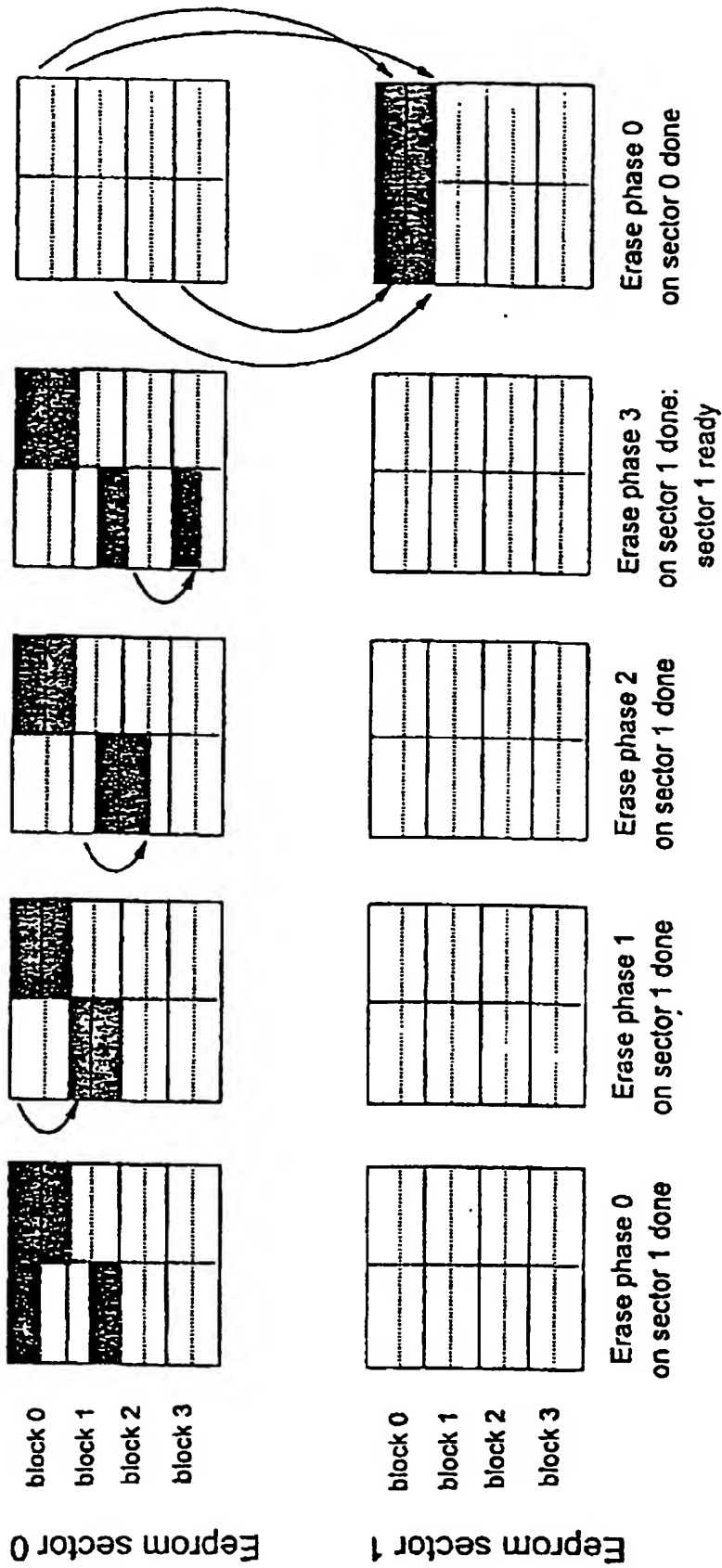


FIG. 3

224000h	FCR
224001h	ECR
224002h	FSR

FIG. 3A

Sector	Addresses	Max Size
OTP	211F80h to 211FFFh	128 byte
Flash 0	000000h to 00FFFFh	64 Kbyte
Flash 1	010000h to 01BFFFh	48 Kbyte
Flash 2	01C000h to 01DFFFh	8 Kbyte
Flash 3	01E000h to 01FFFFh	8 Kbyte
Eeprom	220000h to 2203FFh	1 Kbyte

FIG. 3B

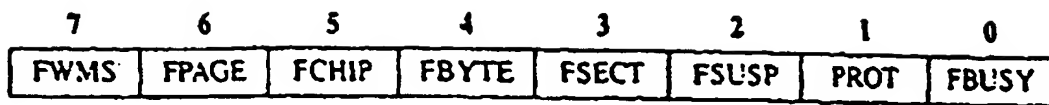


FIG. 3C

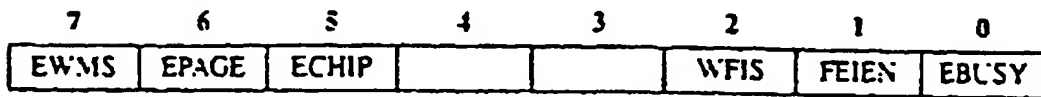


FIG. 3D

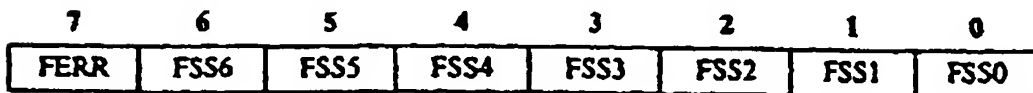


FIG. 3E

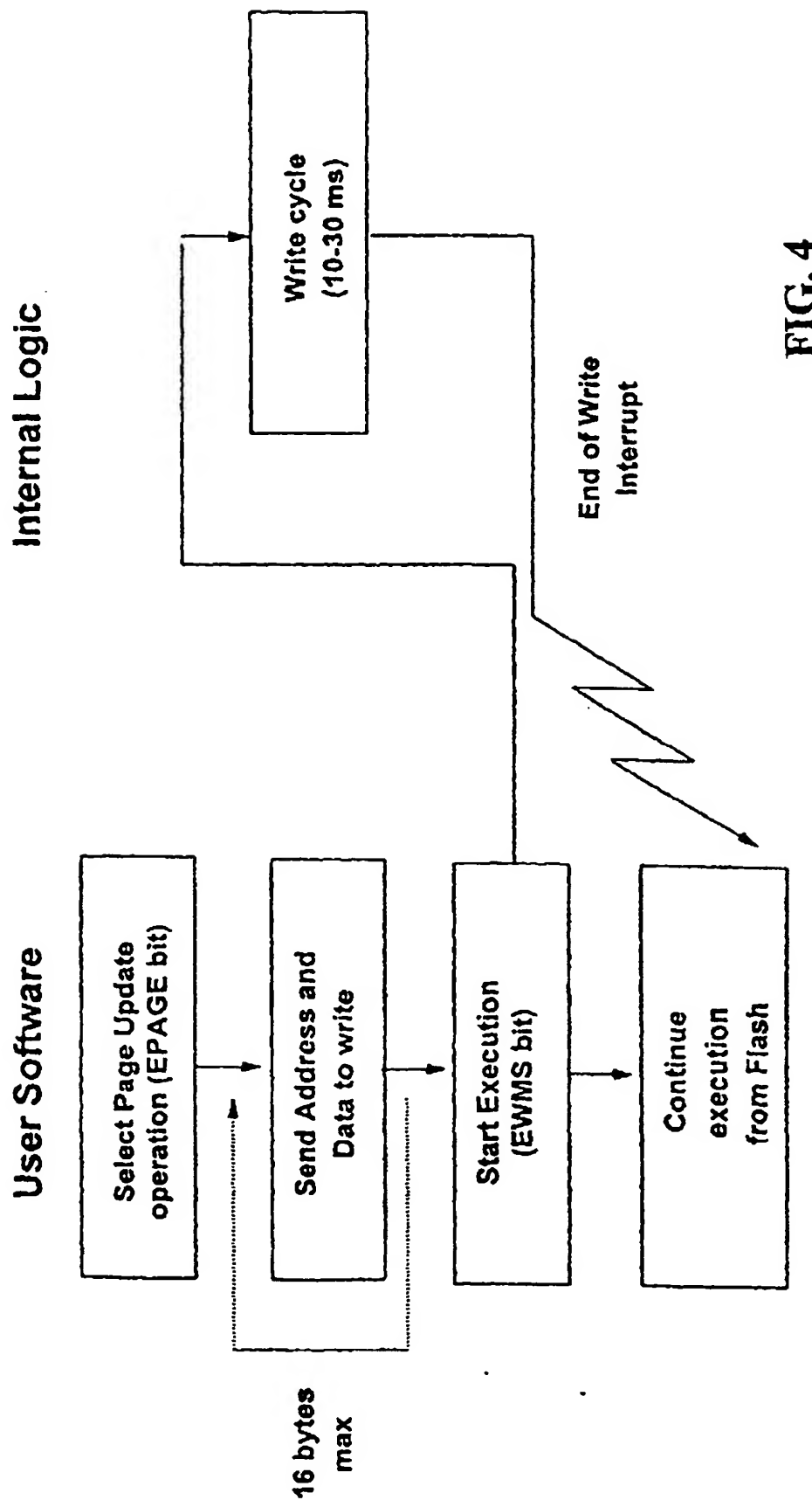


FIG. 4

211FFCh	NVAPR
211FFDh	NVWPR
211FFEh	SVPWD0
211FFh	SVPWD1

FIG. 4A

Operation	Size	Min	Typ	Max
Page Update	256 byte	160 us	10 ms	30 ms
	512 byte	160 us	15 ms	50 ms
	1 Kbyte	160 us	30 ms	100 ms
Chip Erase	256 byte		35 ms	100 ms
	512 byte		45 ms	150 ms
	1 Kbyte		70 ms	300 ms

FIG. 4B

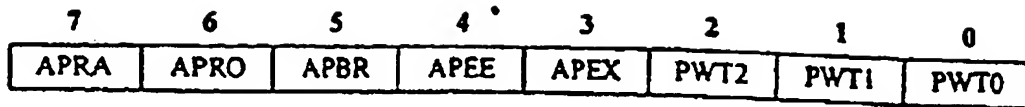


FIG. 4C

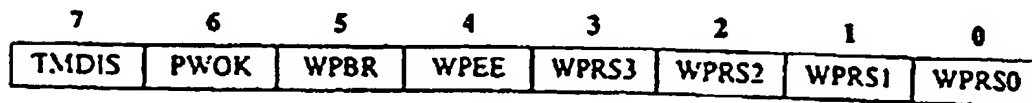


FIG. 4D

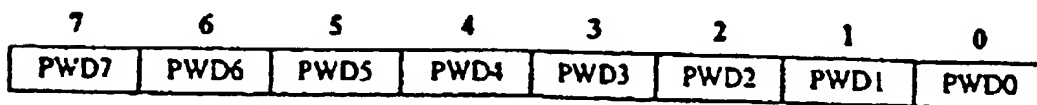


FIG. 4E

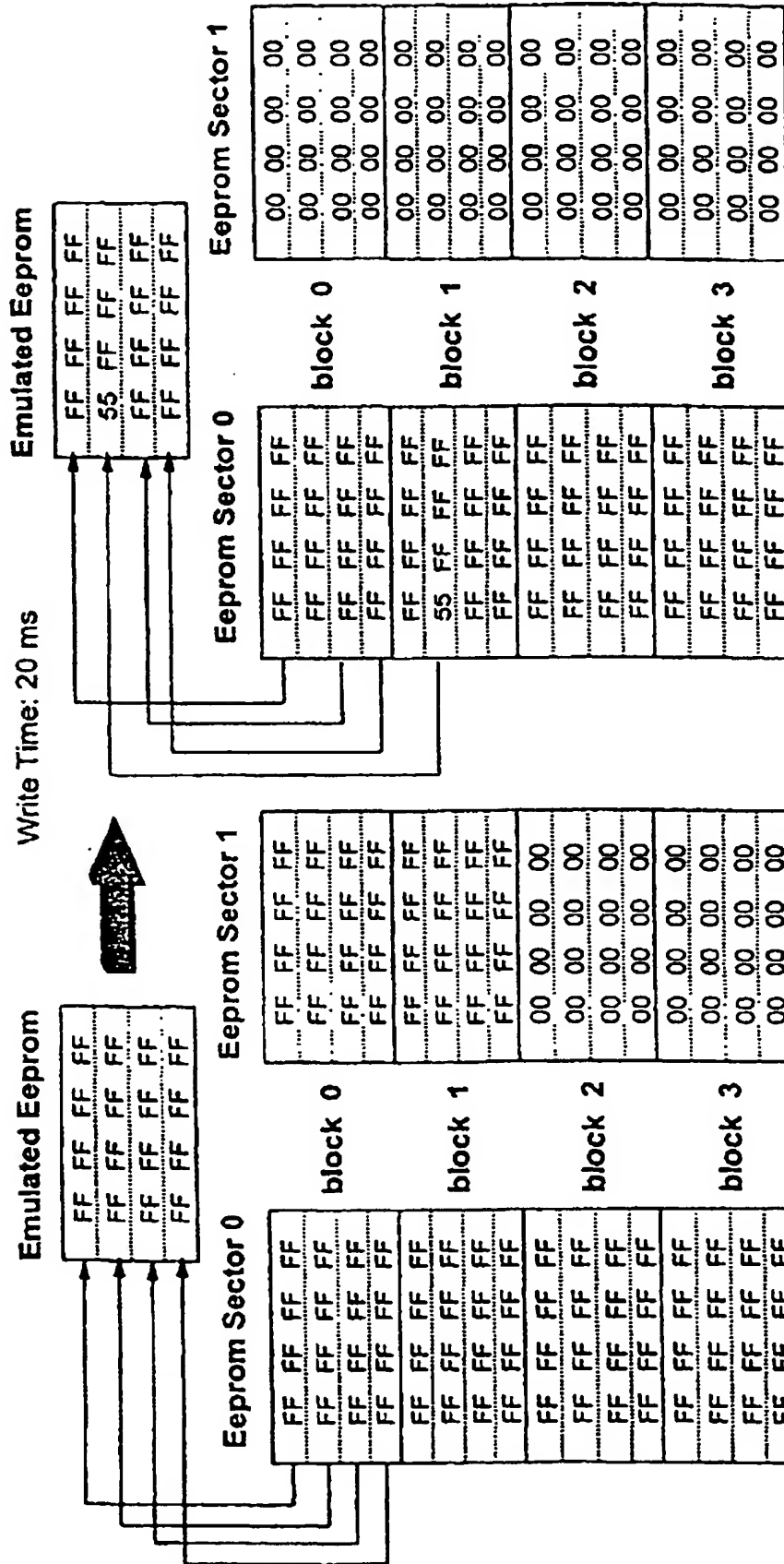


FIG. 5

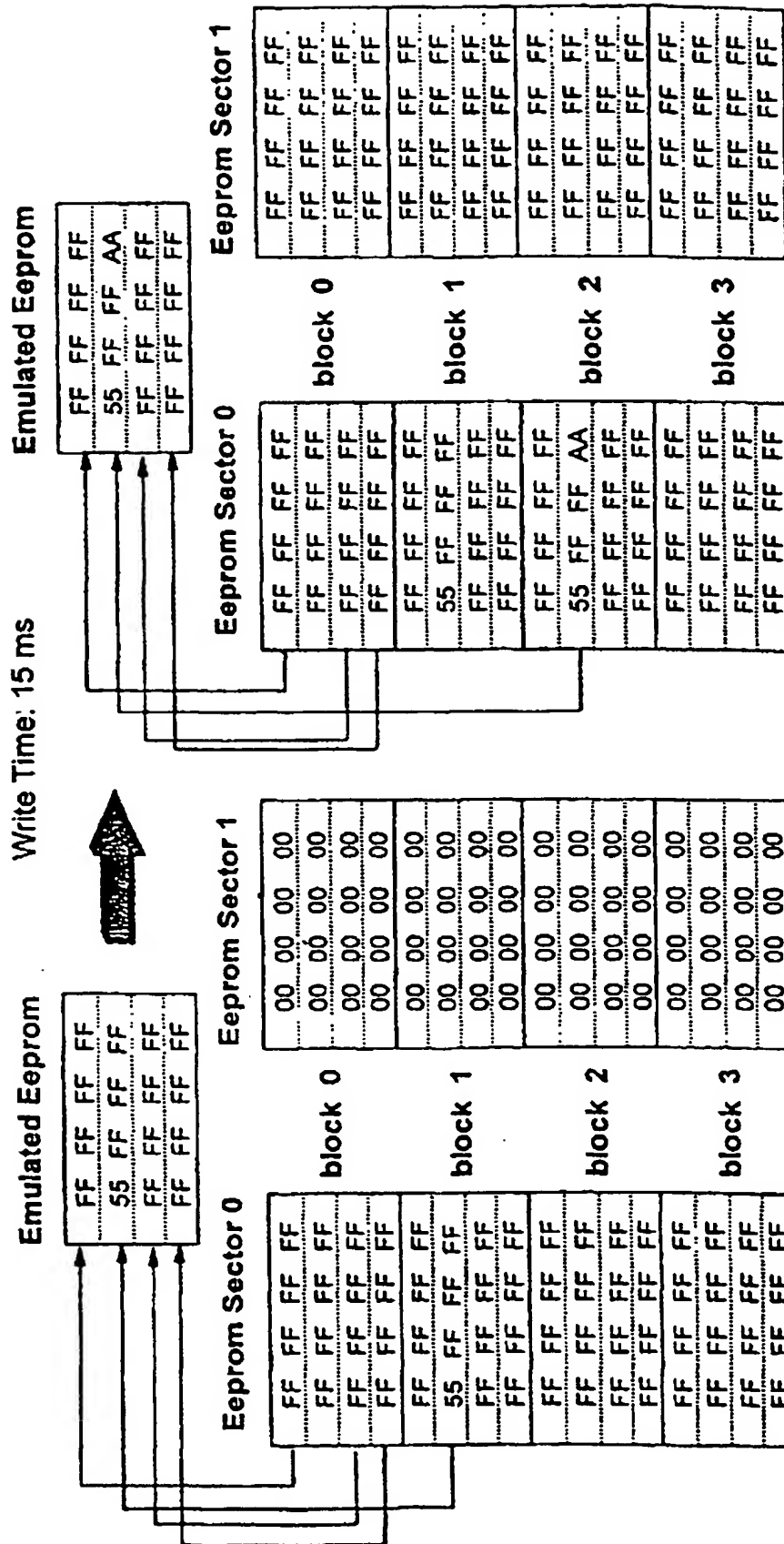


FIG. 6

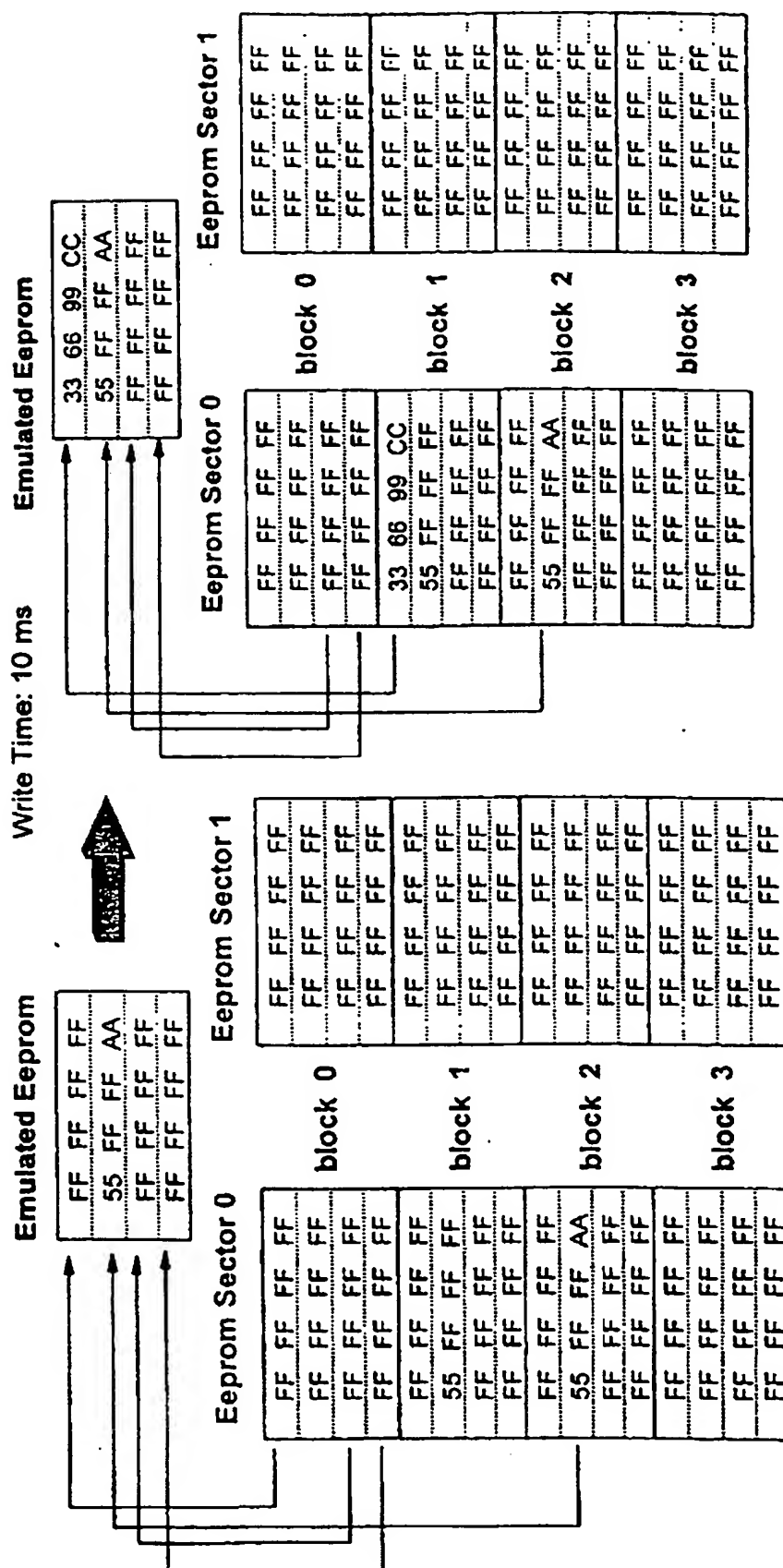


FIG. 7

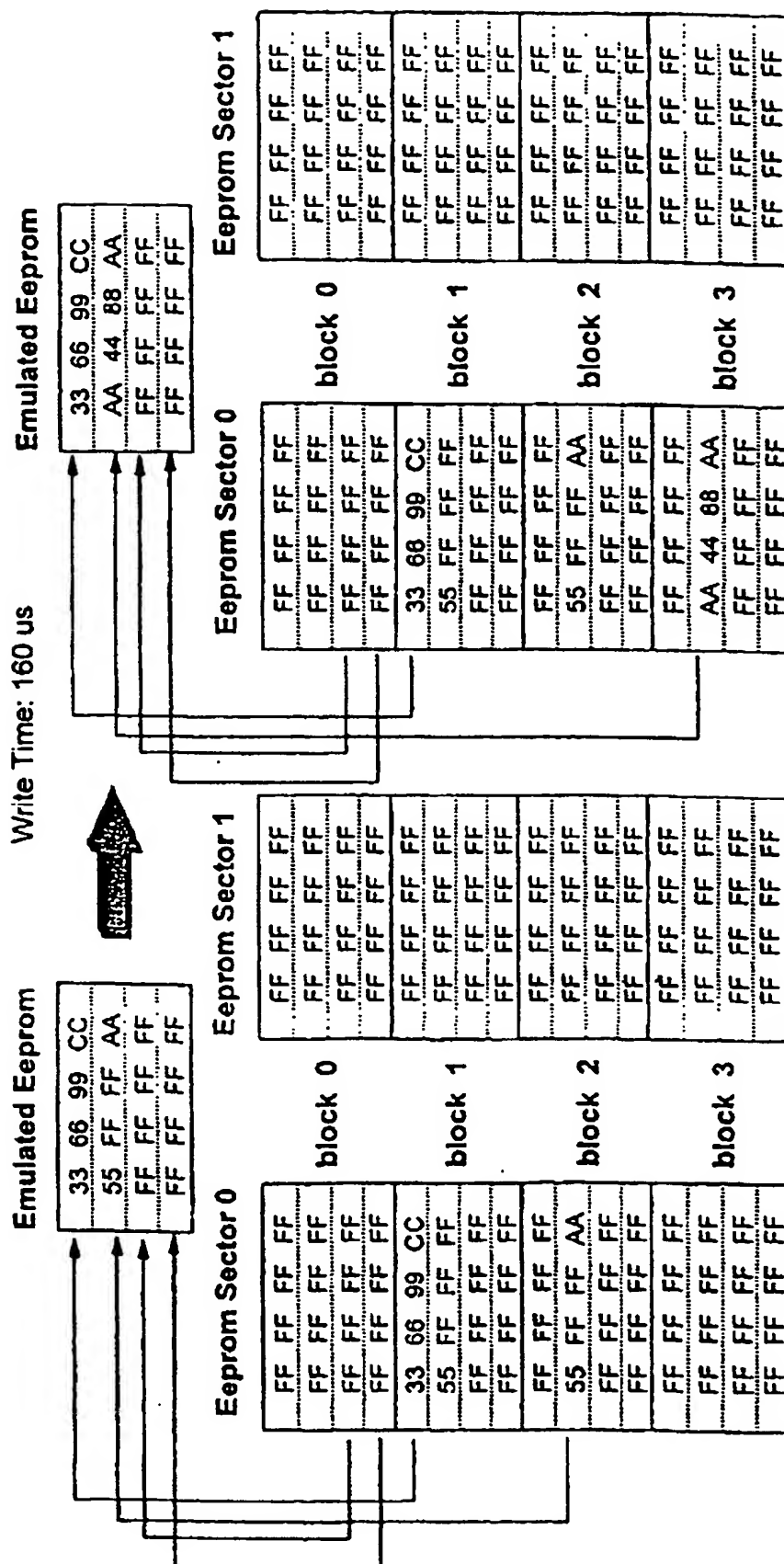


FIG. 8

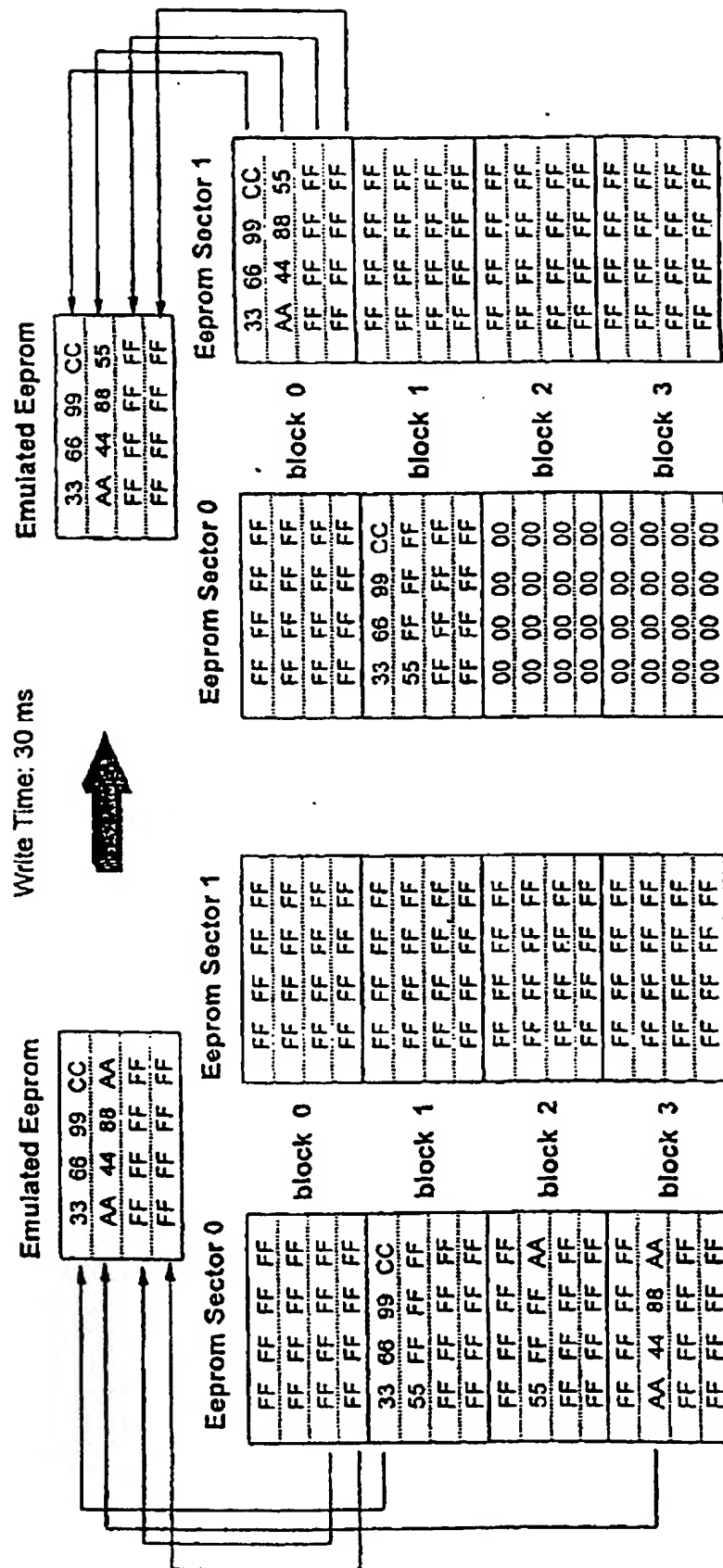


FIG. 9

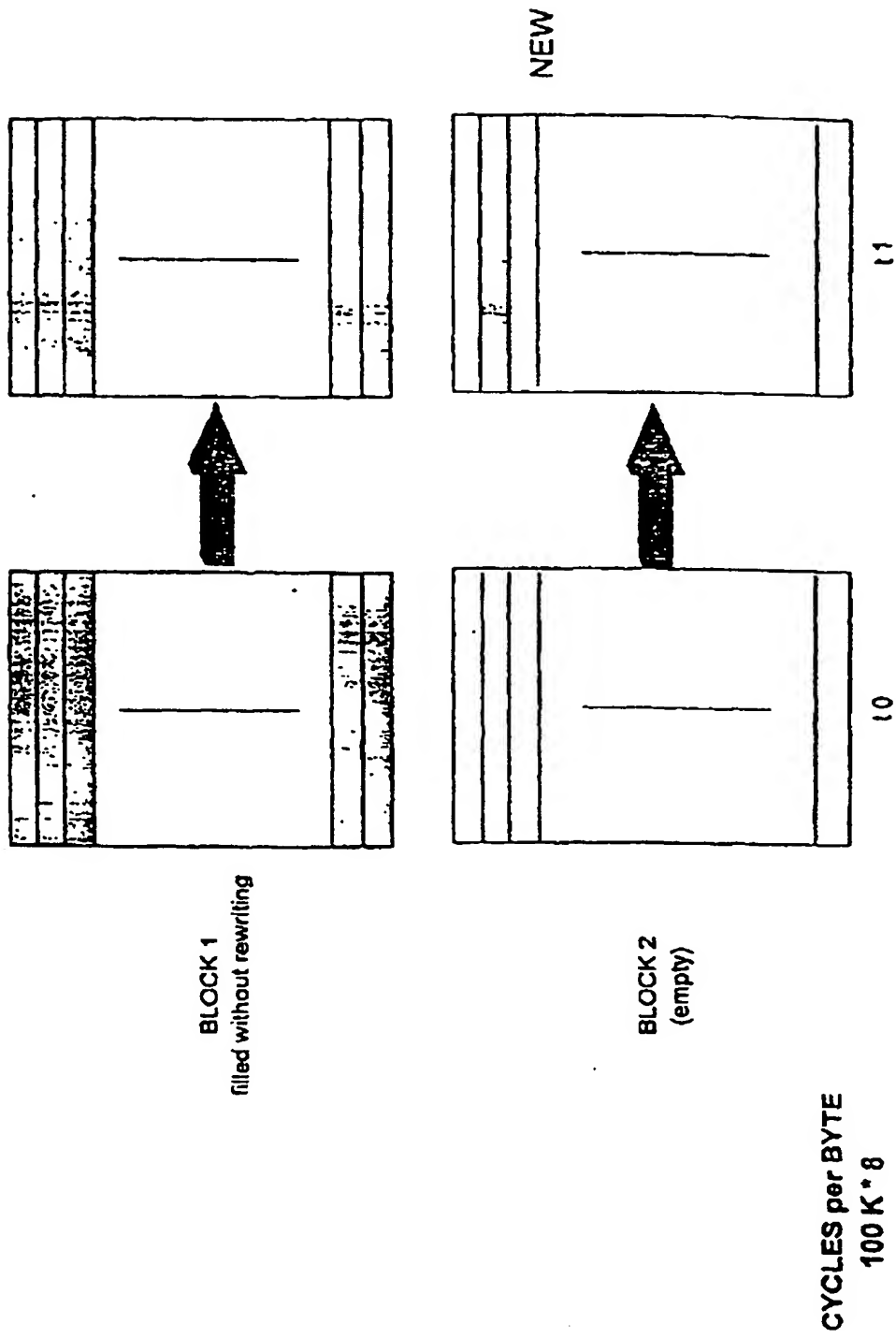


FIG. 10

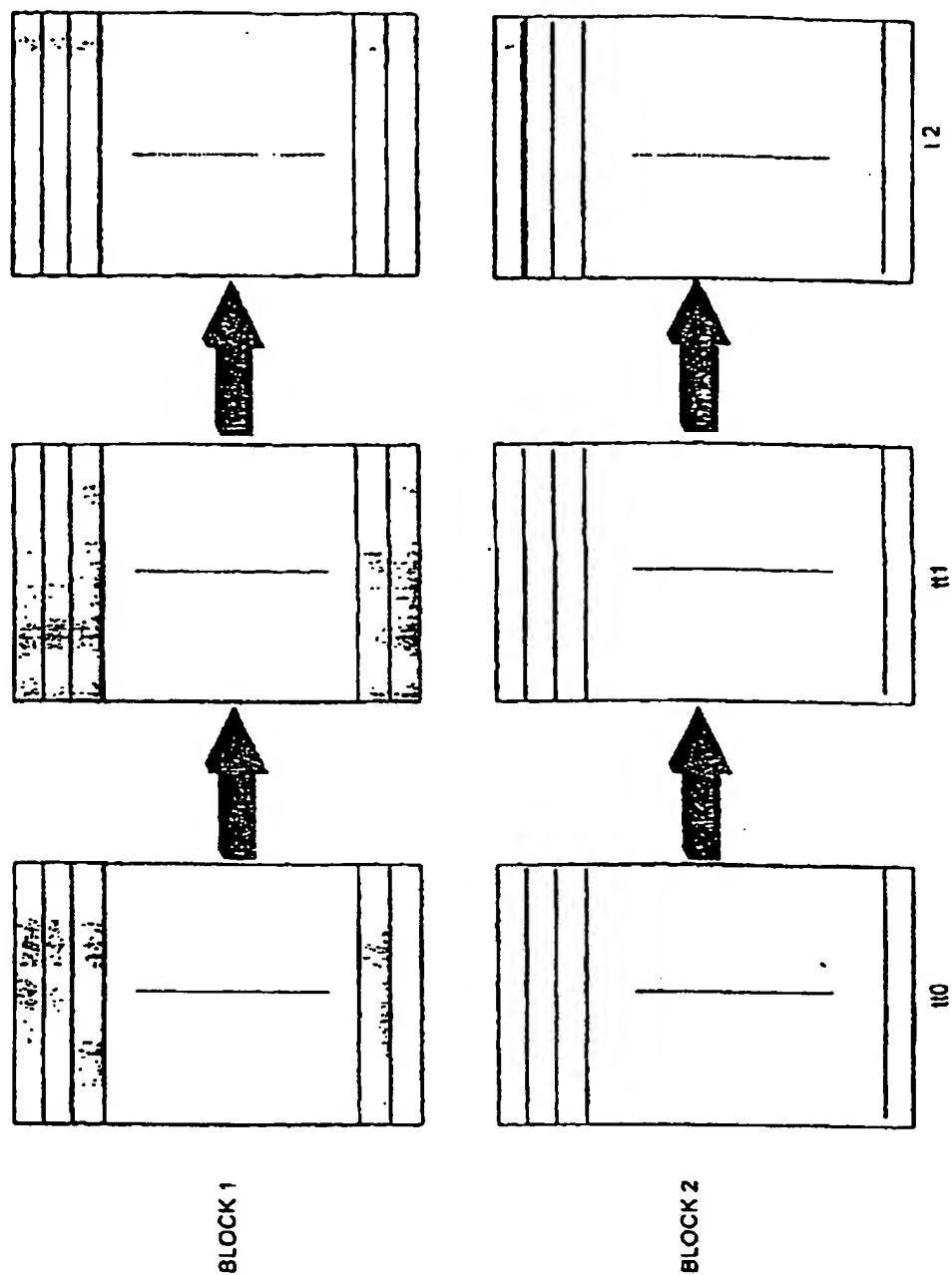
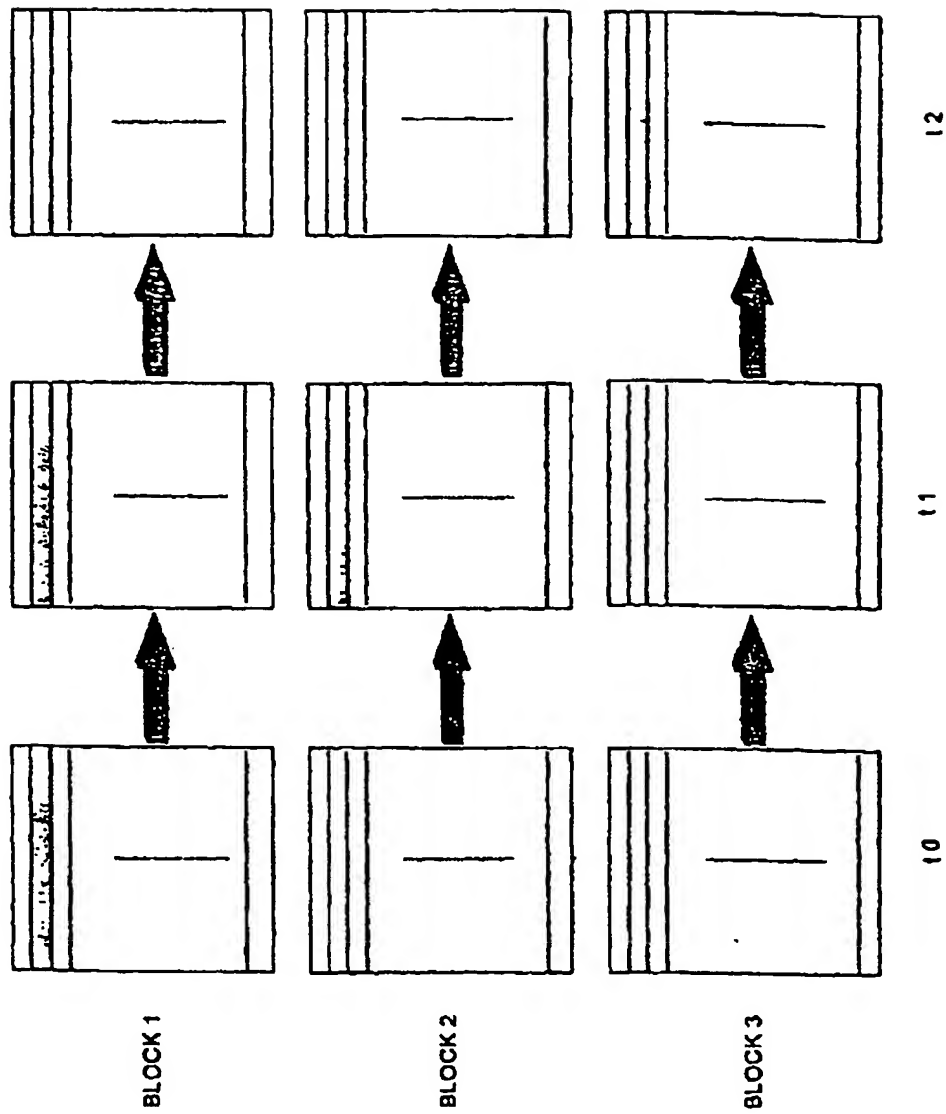


FIG. 11

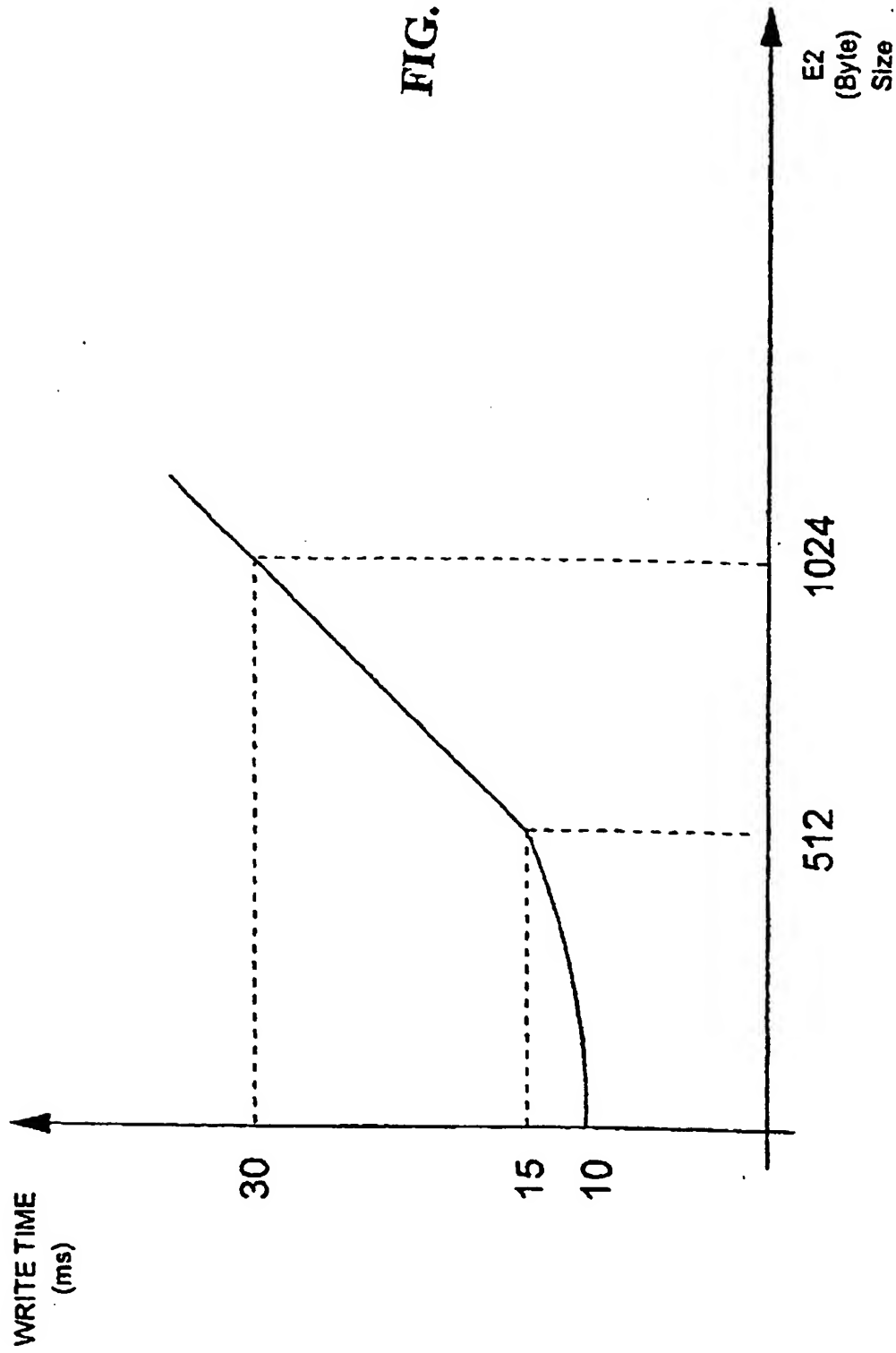
CYCLES per BYTE
 $100K \cdot 8 / 1K \cdot 64 = 51200$



CYCLES per BYTE
100K * 8 / 1K = 800

FIG. 12

FIG. 13



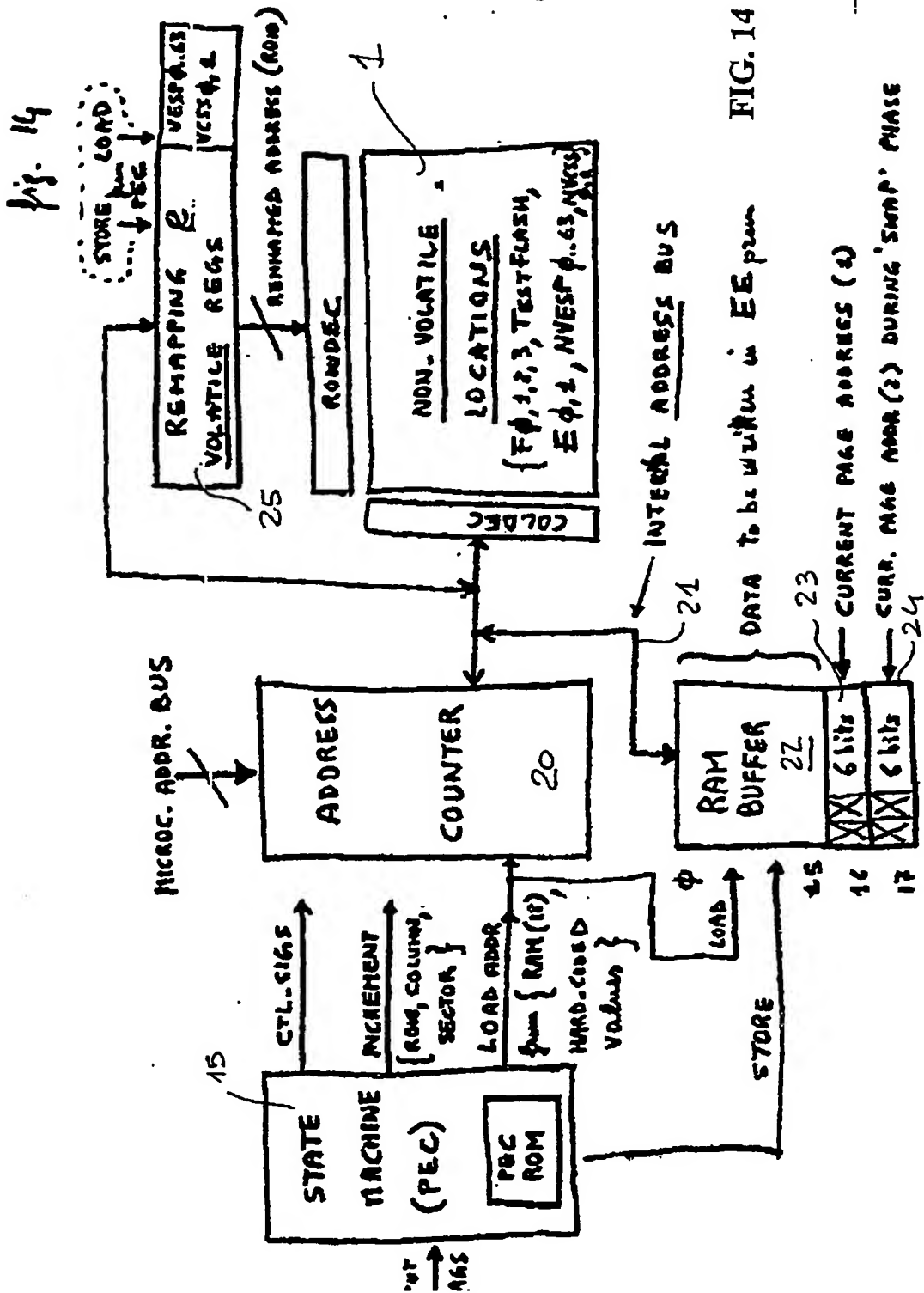


FIG. 14



European Patent
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EUROPEAN SEARCH REPORT

Application Number
EP 98 20 3302

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (InCL6)
Y	US 5 796 657 A (TSAO HSING-YA ET AL) 18 August 1998	1,2,10	611C16/06
A	* column 1, line 20 - column 3, line 13 * * column 4, line 35 - column 5, line 5 * * column 11, line 30 - line 53 * * figure 1 *	4,8	
Y	ATMEL: Secure Microcontrollers - Data Sheets, Secure Cryptocontrollers for Smart Cards; AT90SCC SUMMARY, updated 22 June 1998. Available from Internet: <URL:http://www.atmel.com/atmel/products/prod153.htm> 22 February 1998. XP002094247	1,2,10	
A	* page 1 - page 4 *	7	
A	BAHOUT Y: "Combined FLASH and EEPROM integrated circuit" ELEKTRONIK INDUSTRIE, OCT. 1997, HUTHIG, GERMANY, vol. 28, no. 10, pages 48, 50-51, XP002094246 ISSN 0374-3144 * the whole document *	1,2,9,10	TECHNICAL FIELDS SEARCHED (InCL6) 611C
A	US 5 651 128 A (GAULTIER JEAN-MARIE) 22 July 1997 * column 1, line 15 - column 3, line 8 *	5	
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 26 February 1999	Examiner Colling, P
<p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document</p>			

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